

FORMATION OF A METAL VIA STRUCTURE FROM A COMPOSITE METAL LAYER

ABSTRACT

A process for creating narrow, metal via structures, used to connect metallization levels, has been developed. The process features initially forming a narrow, metal via structure, and then an underlying interconnect metallization structure, from a single, composite metallization layer. The composite metallization layer is composed of conductive layers, with a specific layer used as an etch stop, allowing creation of a narrow metal via structure, from the top layer of the composite metallization layer, without disturbing the bottom layers. The bottom layers of the composite metallization layer are then patterned to create the underlying interconnect metallization structure.

(FIGURE 1 IS SUGGESTED FOR PUBLICATION)